



GENERAL DESCRIPTION

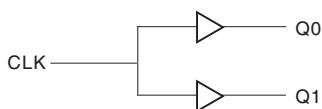


The ICS8302I is a low skew, 1-to-2 LVCMOS Fanout Buffer and a member of the HiPerClockSTM family of High Performance Clock Solutions from ICS. The ICS8302I has a single ended clock input. The single ended clock input accepts LVCMOS or LVTTTL input levels. The ICS8302I features a pair of LVCMOS outputs. The ICS8302I is characterized at full 3.3V for input V_{DD} , and mixed 3.3V and 2.5V for output operating supply modes (V_{DDO}). Guaranteed output and part-to-part skew characteristics make the ICS8302I ideal for clock distribution applications demanding well defined performance and repeatability.

FEATURES

- 2 LVCMOS / LVTTTL outputs
- LVCMOS / LVTTTL clock input accepts LVCMOS or LVTTTL input levels
- Maximum output frequency: 200MHz
- Output skew: 40ps (typical)
- Part-to-part skew: 250ps (typical)
- Small 8 lead SOIC package saves board space
- Full 3.3V or 3.3V core, 2.5V supply modes
- -40°C to 85°C ambient operating temperature
- Lead-Free package fully RoHS compliant

BLOCK DIAGRAM



PIN ASSIGNMENT

V_{DDO}	1	8	Q0
V_{DD}	2	7	GND
CLK	3	6	V_{DDO}
GND	4	5	Q1

ICS8302I 8-Lead SOIC

3.8mm x 4.8mm, x 1.47mm package body

M Package
Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 6	V_{DDO}	Power		Output supply pins.
2	V_{DD}	Power		Core supply pin.
3	CLK	Input	Pulldown	LVCMOS / LVTTTL clock input.
4,7	GND	Power		Power supply ground.
5	Q1	Output		Single clock output. LVCMOS / LVTTTL interface levels.
8	Q0	Output		Single clock output. LVCMOS / LVTTTL interface levels.

NOTE: *Pulldown* refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
C_{PD}	Power Dissipation Capacitance (per output)	$V_{DD}, V_{DDO} = 3.465V$		22		pF
		$V_{DD} = 3.465V, V_{DDO} = 2.625V$		16		pF
$R_{PULLDOWN}$	Input Pulldown Resistor			51		k Ω
R_{OUT}	Output Impedance			7		Ω



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to $V_{DD} + 0.5V$
Outputs, V_O	-0.5V to $V_{DDO} + 0.5V$
Package Thermal Impedance, θ_{JA}	112.7°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Power Supply Voltage		3.135	3.3	3.465	V
I_{DD}	Power Supply Current				14	mA
I_{DDO}	Output Supply Current				5	mA

TABLE 3B. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		2.375	2.5	2.625	V
I_{DD}	Power Supply Current				14	mA
I_{DDO}	Output Supply Current				5	mA

TABLE 3C. LVCMOS / LVTTTL DC CHARACTERISTICS, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^\circ\text{C}$ TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage		-0.3		1.3	V
I_{IH}	Input High Current	CLK $V_{DD} = V_{IN} = 3.465V$			150	μA
I_{IL}	Input Low Current	CLK $V_{DD} = 3.465V, V_{IN} = 0V$	-5			μA
V_{OH}	Output High Voltage	50Ω to $V_{DDO}/2$	2.6			V
		$I_{OH} = -100\mu\text{A}$	2.9			V
V_{OL}	Output Low Voltage	50Ω to $V_{DDO}/2$			0.5	V
		$I_{OL} = 100\mu\text{A}$			0.2	V



TABLE 3D. LVCMOS / LVTTTL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage		-0.3		1.3	V
I_{IH}	Input High Current	CLK $V_{DD} = V_{IN} = 3.465V$			150	μA
I_{IL}	Input Low Current	CLK $V_{DD} = 3.465V$, $V_{IN} = 0V$	-5			μA
V_{OH}	Output High Voltage	50Ω to $V_{DDO}/2$	1.8			V
		$I_{OH} = -100\mu A$	2.2			V
V_{OL}	Output Low Voltage	50Ω to $V_{DDO}/2$			0.5	V
		$I_{OL} = 100\mu A$			0.2	V

TABLE 4A. AC CHARACTERISTICS, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				200	MHz
tp_{LH}	Propagation Delay, Low-to-High; NOTE 1	$f \leq 200MHz$	1.9	2.35	2.8	ns
$tsk(o)$	Output Skew; NOTE 2, 4			40	105	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4			250	800	ps
t_R	Output Rise Time	20% to 80%	300		800	ps
t_F	Output Fall Time	20% to 80%	300		800	ps
odc	Output Duty Cycle	$f \leq 133MHz$	45		55	%
		$133MHz < f \leq 200MHz$	40		60	%

Parameters measured at f_{MAX} unless otherwise noted.

NOTE 1: Measured from $V_{DD}/2$ of the input to $V_{DDO}/2$ of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at $V_{DDO}/2$.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

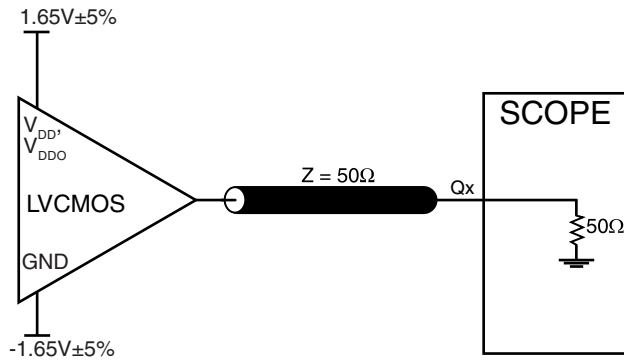
TABLE 4B. AC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				200	MHz
tp_{LH}	Propagation Delay, Low-to-High; NOTE 1	$f \leq 200MHz$	2.3		3.3	ns
$tsk(o)$	Output Skew; NOTE 2, 4				110	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4			250	800	ps
t_R	Output Rise Time	20% to 80%	250		650	ps
t_F	Output Fall Time	20% to 80%	250		650	ps
odc	Output Duty Cycle	$f \leq 133MHz$	45		55	%
		$133MHz < f \leq 200MHz$	40		60	%

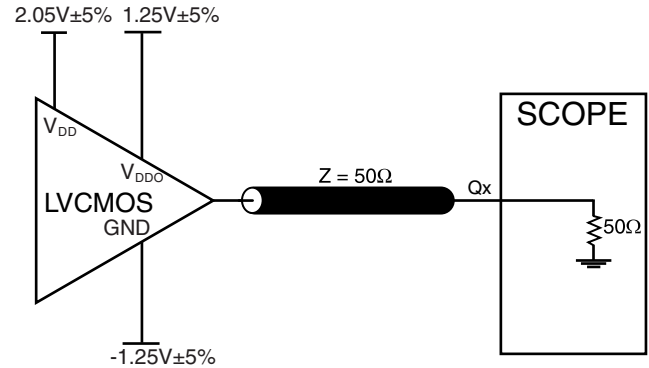
See Table 4A above for notes.



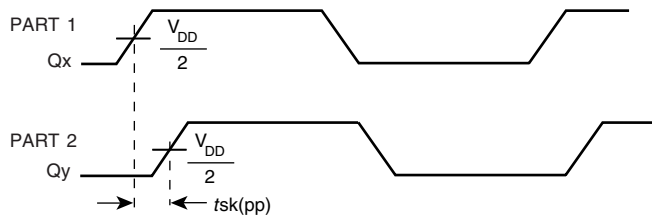
PARAMETER MEASUREMENT INFORMATION



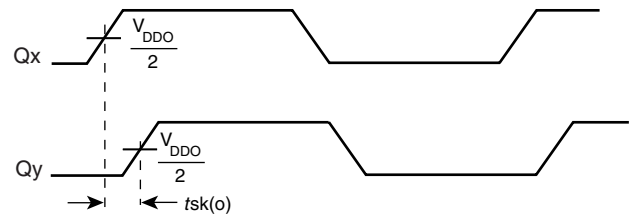
3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT



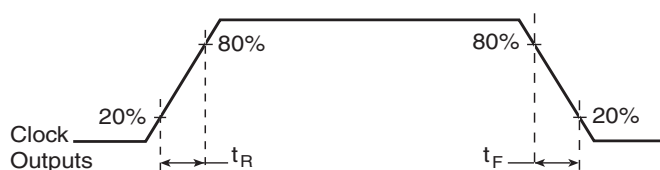
3.3V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT



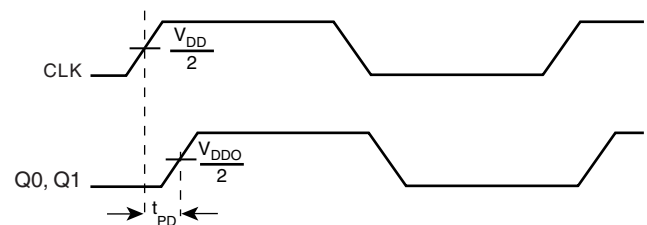
PART-TO-PART SKEW



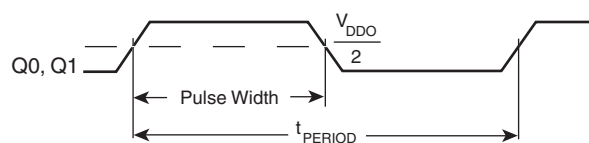
OUTPUT SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



$$odc = \frac{t_{PW}}{t_{PERIOD}}$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



RELIABILITY INFORMATION

TABLE 5. θ_{JA} VS. AIR FLOW TABLE FOR 8 LEAD SOIC

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8302I is: 322



PACKAGE OUTLINE - SUFFIX M FOR 8 LEAD SOIC

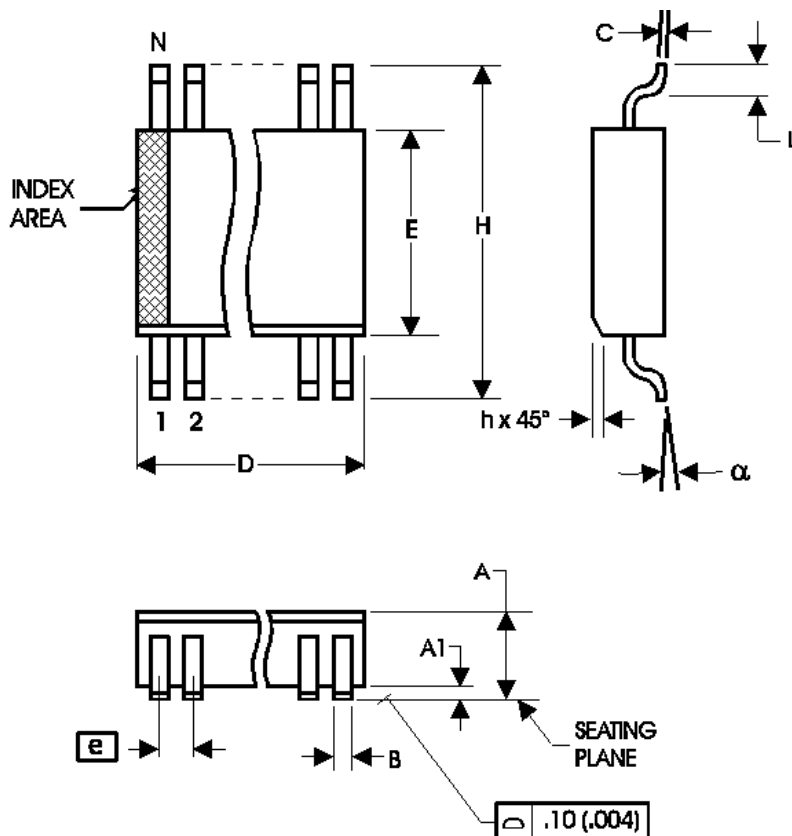


TABLE 6. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MINIMUM	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012



Integrated
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ICS8302I

LOW SKEW, 1-TO-2 LVCMOS / LVTTTL FANOUT BUFFER

TABLE 7. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8302AMI	8302AMI	8 lead SOIC	tube	-40°C to 85°C
8302AMIT	8302AMI	8 lead SOIC	2500 tape & reel	-40°C to 85°C
8302AMILF	8302AMIL	8 lead "Lead-Free" SOIC	tube	-40°C to 85°C
8302AMILFT	8302AMIL	8 lead "Lead-Free" SOIC	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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ICS8302I
LOW SKEW, 1-TO-2
LVCMOS / LVTTTL FANOUT BUFFER

REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
A	T7	1 8	Features Section - added Lead-Free bullet. Ordering Information Table - added Lead-Free part number.	3/24/05